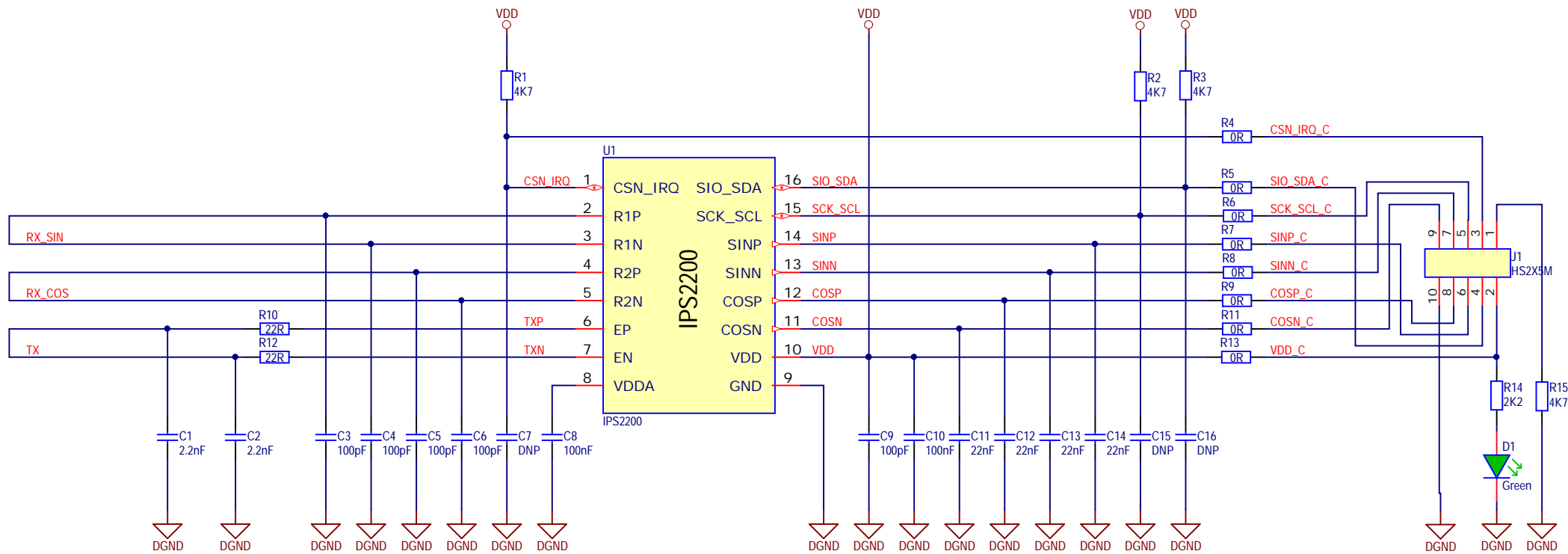





IPS2200MROT09004

Date: 10MAY2019
Project: IPS2200MROT09004
Version: 3.1
Content: Schematic
Coil PCB Layout
Coil PCB 3D Model
Bill of Materials
PCB Manufacture Requirements
Coil Layer Stack
Target PCB Layout
Target PCB 3D Model



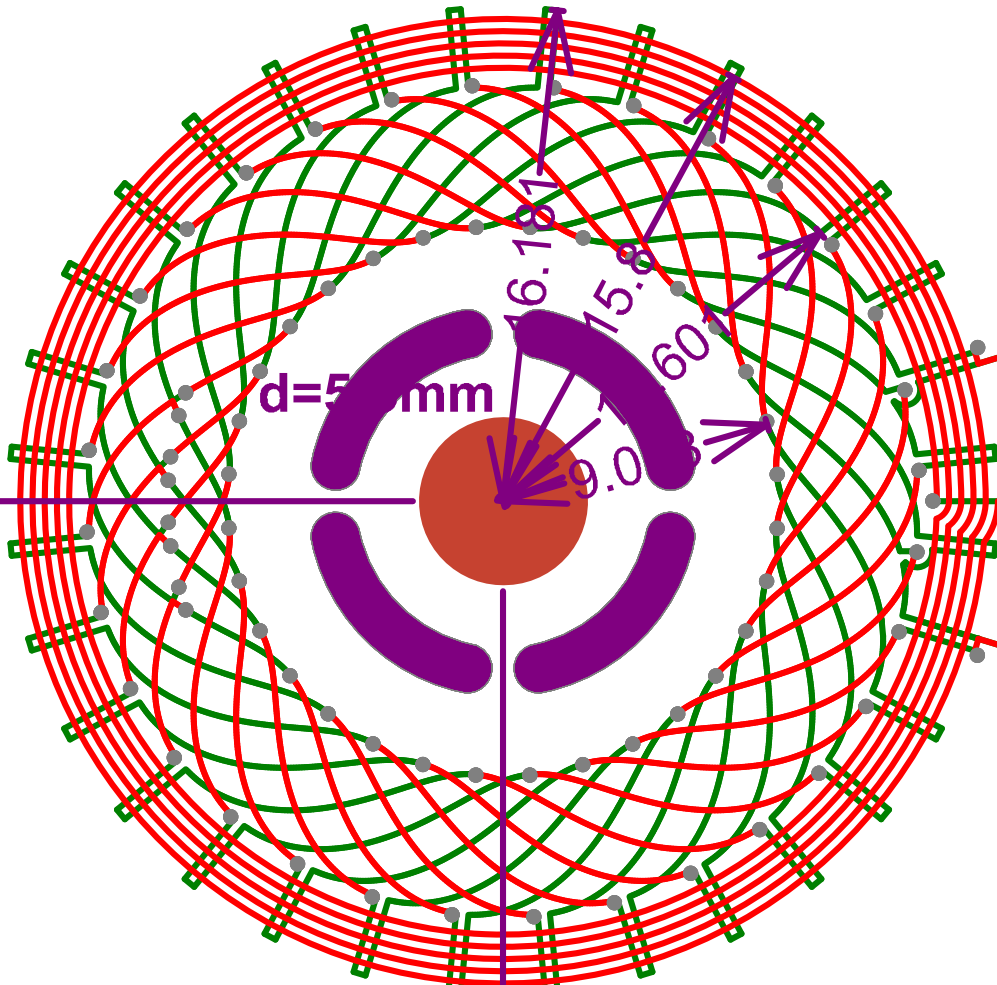
DNP = EMC placeholder, populate if needed
 OR = EMC placeholder, adjust if needed

| | | | |
|----------------------------------|---------------|--------------------|---|
| Title: IPS2200MROT9004 | | |  www.IDT.com |
| Project: IPS2200MROT09004.PrjPCB | | | |
| Size: A4 | Sheet: 1 of 1 | Drawn by: B.Gombor | Version: 3.1 |
| File: IPS2200MROT09004.SCHDOC | | | Date: 27.05.2019 |

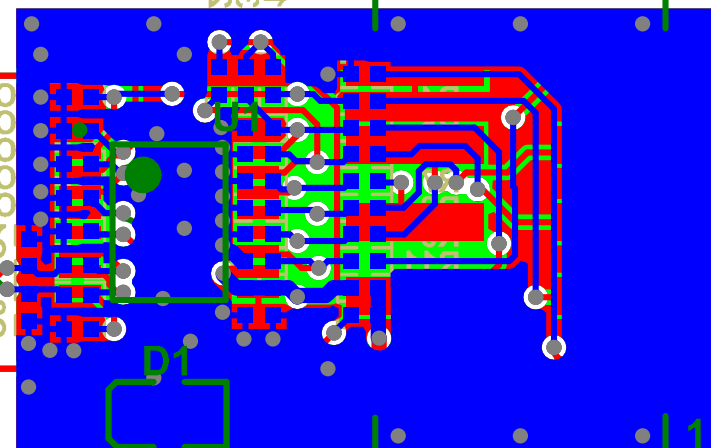
IPS2200/APPLICATION MODULE



10MAX2019 V3:1



d=2.5mm
R_42_IPS2200_4x90_OD34_ID14



PWR_ON

- GND
- COSP
- SINP
- SIO_SDA
- VDD
- COSN
- SINN
- SCK_SCL
- CSN_IRQ
- ID

40,00
35,00
17,50
2,50
2,50














17,50
35,00
64,00

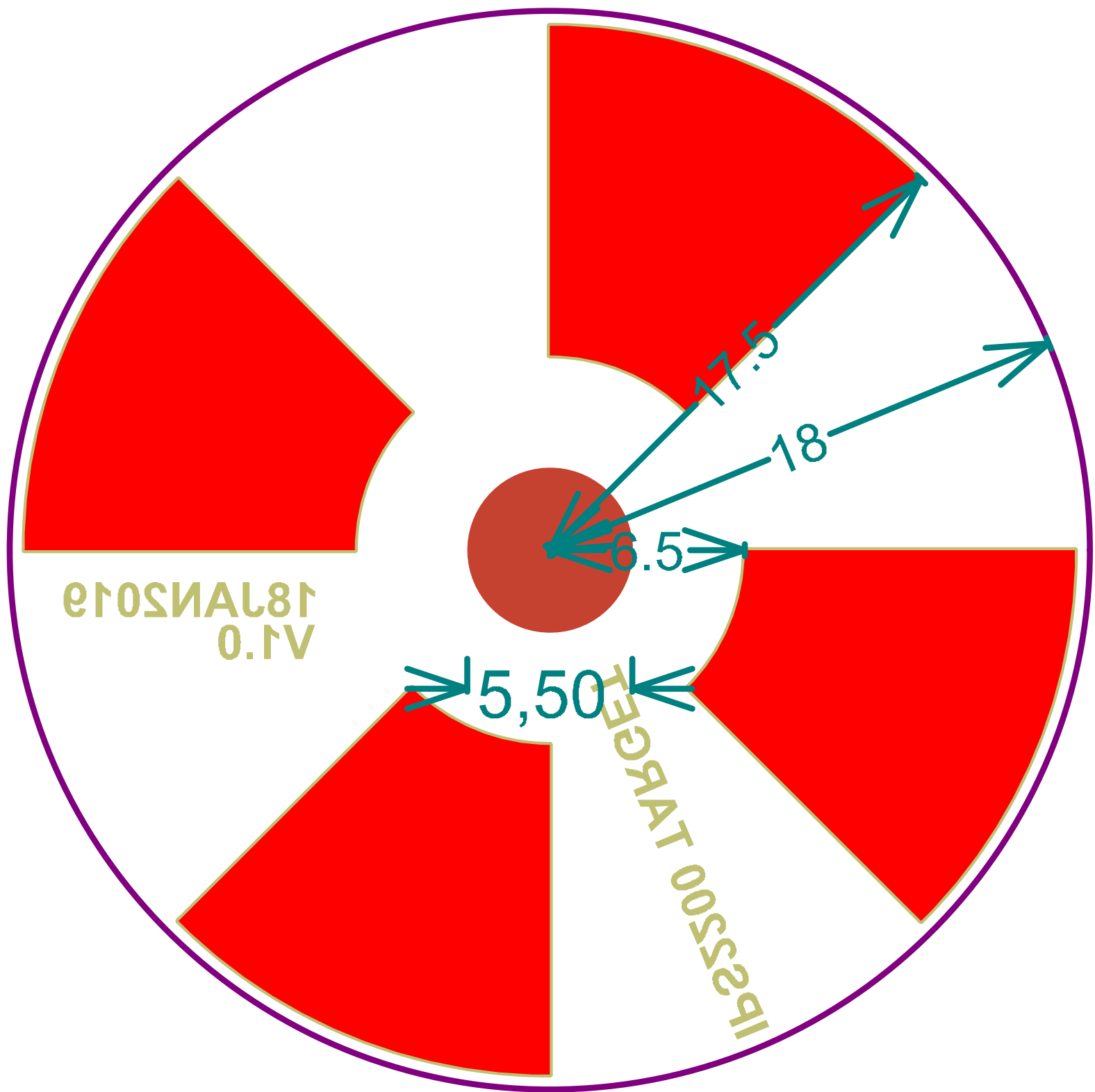
| Designator | Footprint | Value | Quantity |
|----------------------------------|---------------------|---------|----------|
| C1, C2 | C0402 3D | 2.2nF | 2 |
| C3, C4, C5, C6, C9 | C0402 3D | 100pF | 5 |
| C7, C15, C16 | C0402 3D | DNP | 3 |
| C8, C10 | C0402 3D | 100nF | 2 |
| C11, C12, C13, C14 | C0402 3D | 22nF | 4 |
| D1 | LED0805 G 3D | Green | 1 |
| J1 | T821M110A1S100CEU-B | HS2X5M | 1 |
| R1, R2, R3, R15 | R0402 3D | 4K7 | 4 |
| R4, R5, R6, R7, R8, R9, R11, R13 | R0402 3D | 0R | 8 |
| R10, R12 | R0402 3D | 22R | 2 |
| R14 | R0402 3D | 2K2 | 1 |
| U1 | TSSOP16_NVT02006 | IPS2200 | 1 |

Manufacturing requirements

| | |
|-----------------------------------|-------------------------|
| Name | IPS2200MROT09004_GERBER |
| Number of layers | 4 |
| Base material | FR-4 |
| Thickness | 1.0 mm +/- 10% |
| Thickness of copper coating | 35 µm |
| Final cover | ENIG |
| Minimal copper width | 0.2 mm |
| Minimal copper to copper distance | 0.15 mm |
| Via hole/pad diameter | 0.2/0.5 mm |
| Slotted holes | no |
| Panel dimensions | 64 x 40 mm |
| Silk screen color | white on both sides |
| Solder mask color | green |

Board Stack Report

| Stack Up | | Layer Stack | | | |
|----------|---|----------------|---------------|-----------|----------|
| Layer | Board Layer Stack | Name | Material | Thickness | Constant |
| 1 |  | Top Paste | | | |
| 2 |  | Top Overlay | | | |
| 3 |  | Top Solder | Solder Resist | 0,030mm | 3,5 |
| 4 |  | Top Layer | Copper | 0,035mm | |
| 5 |  | Dielectric 1 | FR-4 | 0,200mm | 4,2 |
| 6 |  | Inner Layer 1 | Copper | 0,035mm | |
| 7 |  | Dielectric 3 | | 0,400mm | 4,2 |
| 8 |  | InnerLayer 2 | Copper | 0,035mm | |
| 9 |  | Dielectric 2 | | 0,200mm | 4,2 |
| 10 |  | Bottom Layer | Copper | 0,035mm | |
| 11 |  | Bottom Solder | Solder Resist | 0,030mm | 3,5 |
| 12 |  | Bottom Overlay | | | |
| 13 |  | Bottom Paste | | | |
| | Height : 1,000mm | | | | |



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TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

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